

Notice of References Cited	Application/Control No. 10/791,569	Applicant(s)/Patent Under Reexamination UENO, TAKASHI	
	Examiner Sikyln lp	Art Unit 1742	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-4,818,283	04-1989	Grunthaler et al.	419/67
	B	US-			
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	D	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

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	N					
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Chu, J. P.; Lin, T. N., Deposition, microstructure and properties of sputtered copper films containing insoluble molybdenum, Journal of Applied Physics (1999), 85(9), 6462-6469□□□□□□
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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